



High-Speed USB 2.0 (480-Mbps) 1:2 Multiplexer/Demultiplexer Switch

1 FEATURES

-3dB Bandwidth: 550MHzSupply Range: +1.8V to +5.5V

• Ron is Typically 6Ω

Fast Switching Times:

ton 20ns toff 15ns

Break-Before-Make Switching

Low Power Consumption (1μA Maximum)

• Rail-to-Rail Input and Output Operation

 Extended Industrial Temperature Range: -40°C to +85°C

 Micro Size Packages: MSOP10, UQFN1.4X1.8-10

2 APPLICATIONS

- Routes Signals for USB 1.0, 1.1, and 2.0
- MP3 and Other Personal Media Players
- Portable Instrumentation
- USB Switching
- Digital Cameras
- Set-Top Box
- Cell Phones
- PDAs

3 DESCRIPTIONS

The RS2227 is a high-speed, low-power double-pole/double-throw (DPDT) analog switch with single Enable. It is designed to operate from 1.8 V to 5.5 V.

The RS2227 has a bus-switch enable pin, \overline{OE} , that can place the signal paths in high impedance. This allows the user to isolate the bus when it is not in use and consume less current.

The RS2227 is a high-bandwidth switch specially designed for the switching of high-speed USB2.0 signals in handset and consumer applications, such as cell phones, digital cameras, and notebooks with hubs or controllers with limited USB I/Os.

The RS2227 is available MSOP10 and UQFN1.4X1.8-10 package. It operates over an ambient temperature range of -40°C to +85°C.

Device Information (1)

PART PACKAGE		BODY SIZE (NOM)
RS2227	UQFN1.4X1.8-10	1.80mm×1.40mm
K3ZZZ/	MSOP10	3.00mm×3.00mm

 For all available packages, see the orderable addendum at the end of the data sheet.

4 FUNCTIONAL BLOCK DIAGRAM

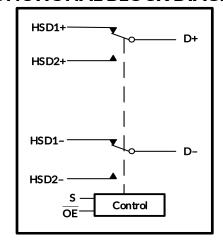




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5 REVISION HISTORY

Note: Page numbers for previous revisions may different from page numbers in the current version.

VERSION	Change Date	Change Item
B.4	2023/05/19	Added the TAPE AND REEL INFORMATION Update package marking
B.4.1	2024/03/11	Modify packaging naming
B.5	2024/05/10	1. Add MSL on Page 6@RevB.4.1 2. Add Package thermal impedance on Page 5@RevB.4.1 3. Update PACKAGE note



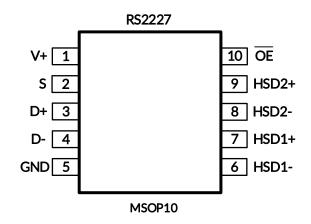
6 PACKAGE/ORDERING INFORMATION (1)

PRODUCT	ORDERING NUMBER	TEMPERATURE RANGE	PACKAGE LEAD	PACKAGE MARKING (2)	MSL (3)	PACKAGE OPTION
RS2227	RS2227XN	-40°C ~+85°C	MSOP10	RS2227	MSL3	Tape and Reel, 4000
K3ZZZ/	RS2227XUTQK10	-40°C ~+85°C	UQFN1.4X1.8-10	2227	MSL3	Tape and Reel, 4000

- (1) This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the right-hand navigation.
- (2) There may be additional marking, which relates to the lot trace code information (data code and vendor code), the logo or the environmental category on the device.
- (3) MSL, The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications.



7 PIN CONFIGURATIONS



7.1 Pin Description

7 12 1 III 2 00011p		
NAME	PIN MSOP10	FUNCTION
V+	1	Power Supply
GND	5	Ground
S	2	Select Input
ŌE	10	Output Enable
HSD1+, HSD2+	7,9	
HSD1-, HSD2-	6,8	Data Port
D+, D-	3,4	

7.2 Function Table

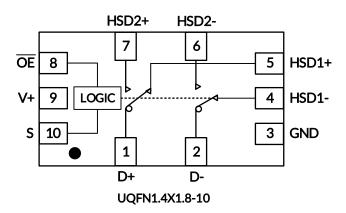
ŌĒ	S	HSD1+, HSD1-	HSD2+, HSD2-
0	0	ON	OFF
0	1	OFF	ON
1	X	OFF	OFF

Note: X =Don't care



PIN CONFIGURATIONS

(TOP VIEW)



Pin Description

<u></u>					
NAME	PIN	FUNCTION			
NAME	UQFN1.4X1.8-10	FONCTION			
V+	9	Power Supply			
GND	3	Ground			
S	10	Select Input			
ŌĒ	8	Output Enable			
HSD1+, HSD2+	5,7				
HSD1-, HSD2-	4,6	Data Port			
D+, D-	1,2				

Function Table

ŌE	S	HSD1+, HSD1-	HSD2+, HSD2-
0	0	ON	OFF
0	1	OFF	ON
1	Х	OFF	OFF

Note: X =Don't care



8 SPECIFICATIONS

8.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted) (1)

SYMBOL	PARAME	PARAMETER		MAX	UNIT
V+	Supply Voltage		-0.3	6.0	V
	Analog, Digital Voltage Range (2)		-0.3	(V+)+0.3	7 °
	Continuous Current HSDn or Dn		-100	+100	^
IPEAK	Peak Current HSDn or Dn		-150	+150	mA
0	D1(3)	MSOP10		200	°C/W
Αιθ	Package thermal impedance (3)	UQFN1.4X1.8-10		115	-C/VV
ΤJ	Junction Temperature (4)		-40	150	°C
T_{stg}	Storage temperature		-65	+150	

⁽¹⁾ Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

8.2 ESD Ratings

The following ESD information is provided for handling of ESD-sensitive devices in an ESD protected area only.

	·	·	VALUE	UNIT
\\\		Human-Body Model (HBM)	±3000	V
V _(ESD)	Electrostatic discharge	Machine Model (MM)	±200	V



ESD SENSITIVITY CAUTION

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

8.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

SYMBOL	PARAMETER	MIN	MAX	UNIT
Vcc	Supply Voltage	1.8	5.5	٧
TA	Operating temperature	-40	+85	°C

⁽²⁾ Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.3V beyond the supply rails should be current-limited to 10mA or less.

⁽³⁾ The package thermal impedance is calculated in accordance with JESD-51.

⁽⁴⁾ The maximum power dissipation is a function of $T_{J(MAX)}$, $R_{\theta JA}$, and T_A . The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{J(MAX)} - T_A) / R_{\theta JA}$. All numbers apply for packages soldered directly onto a PCB.



8.4 Electrical Characteristics

(V+ = \pm 1.8V to \pm 5.5V, GND = 0V, V_{IH} = \pm 1.5V, V_{IL} = \pm 0.5V, T_A = \pm 40°C to \pm 85°C. Typical values are at V+ = \pm 3.3V, T_A = \pm 25°C, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	TA	MIN ⁽²⁾	TYP ⁽³⁾	MAX ⁽²⁾	UNIT
ANALOG SWITCH	•			•			
Analog I/O Voltage (HSD1+, HSD1-, HSD2+, HSD2-)	Vıs		-40°C to +85°C	0		V+	٧
On Resistance	D	V + = 3.0 V , V_{IS} = 0 V to 0.4 V ,	+25°C		6	10	Ω
On-Resistance	Ron	I _D = 8mA, See Figure 1	-40°C to +85°C			10.5	12
On-Resistance Match Between	4 D	V+ = 3.0V, V _{IS} = 0V to 0.4V,	+25°C		0.15	0.6	Ω
Channels	ΔR_{ON}	I _D = 8mA, See Figure 1	-40°C to +85°C			1.6	Ω
On-Resistance Flatness	R _{FLAT} (ON)	$V+ = 3.0V$, $V_{IS} = 0V$ to 1.0V, $I_D = 8$ mA, See Figure 1	+25°C		5	7	
			-40°C to +85°C			8	Ω
Power Off Leakage Current (D+, D-)	loff	$V+ = 0V, V_D = 0V \text{ to } 3.6 \text{ V},$ $V_S, V_{\overline{OE}} = 0V \text{ or } 3.6 \text{ V}$	-40°C to +85°C			1	μΑ
Increase in I+ per Control Voltage	Ісст	V+ = 4.3V, V _S or $V_{\overline{OE}}$ = 2.6 V	-40°C to +85°C			40	μΑ
Source Off Leakage Current	IHSD2(OFF) IHSD1(OFF)	$V+ = 3.6V$, $V_{IS} = 3.3V/0.3V$, $V_D = 0.3V/3.3V$	-40°C to +85°C			1	μΑ
Channel On Leakage Current	I _{HSD2(ON)}	$V+ = 3.6V$, $V_{IS} = 3.3V/ 0.3V$, $V_D = 0.3V/ 3.3V$ or floating	-40°C to +85°C			1	μΑ
DIGITAL CONTROL INPUTS (1)							
Input High Voltage	V _{IH}		-40°C to +85°C	1.6			V
Input Low Voltage	VIL		-40°C to +85°C			0.5	٧
Input Leakage Current	lin	V+ = 3.0V, V _S , $V_{\overline{OE}}$ = 0V or V+	-40°C to +85°C			1	μΑ

⁽¹⁾ All unused digital inputs of the device must be held at V_{IO} or GND to ensure proper device operation.

⁽²⁾ Limits are 100% production tested at 25°C. Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.

⁽³⁾ Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.



Electrical Characteristics (continued) (V+ = +1.8V to +5.5V, GND = 0V, V_{IH} = +1.5V, V_{IL} = +0.5V, T_{A} = -40°C to + 85°C. Typical values are at V+ = +3.3V, T_{A} = +25°C, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	T _A	MIN	TYP	MAX	UNIT		
DYNAMIC CHARACTERISTICS									
Turn-On Time	ton	$V_{IS} = 0.8V, R_L = 50\Omega,$	+25°C		20		ns		
Turn-Off Time	toff	C _L = 10pF, See Figure 2	+25°C		15		ns		
Break-Before-Make Time Delay	t _D	V_{IS} = 0.8V, R_L = 50 Ω , C_L = 10pF, See Figure 3	+25°C		4		ns		
Propagation Delay	t _{PD}	$R_L = 50\Omega$, $C_L = 10pF$	+25°C		0.35		ns		
Off Isolation	Oiso	Signal = 0dBm, R_L = 50 Ω , f = 250MHz, See Figure 4	+25°C		-35		dB		
Channel-to-Channel Crosstalk	XTALK	Signal = 0dBm, R_L = 50 Ω , f = 250MHz, See Figure 5	+25°C		-40		dB		
-3dB Bandwidth	BW	Signal = 0dBm, R_L = 50 Ω , C_L = 5pF, See Figure 6	+25°C		550		MHz		
Channel-to-Channel Skew	tskew	$R_L = 50\Omega$, $C_L = 10pF$	+25°C		0.05		ns		
Charge Injection Select Input to Common I/O	Q	V_G = GND, C_L = 1.0nF, R_G = 0 Ω , Q = C_L x V_{OUT} , See Figure 7	+25°C		11		рС		
HSD+, HSD-, D+, D- ON Capacitance	Con		+25°C		7		pF		
POWER REQUIREMENTS	-		2 , See Figure 5 2 Bm, 2 R _L = 50Ω, 2 +25°C 550 MHz 2 Re Figure 6 +25°C 0.05 ns 2 C _L = 1.0nF, 2 R _G = 0Ω, 2 +25°C 11 pC 2 UT, See Figure 7 +25°C 7 pF						
Power Supply Range	V+		-40°C to +85°C	1.8		5.5	V		
Power Supply Current	I ₊	V + = 3.0 V , V _S , V _{\overline{OE}} = 0 V or V +	-40°C to +85°C			1	μΑ		



9 PARAMETER MEASUREMENT INFORMATION

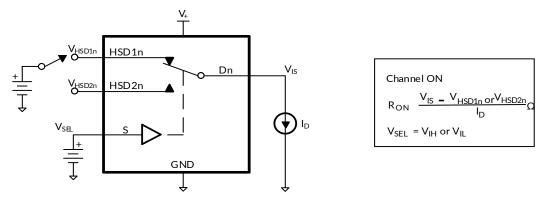


Figure 1. ON-State Resistance (R_{ON})

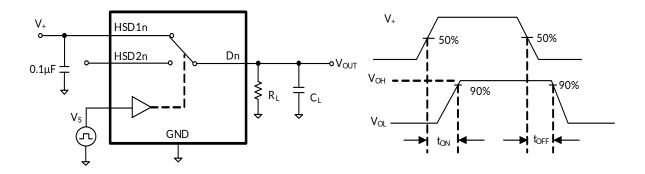


Figure 2. Turn-On (ton) and Turn-Off Time (toff)

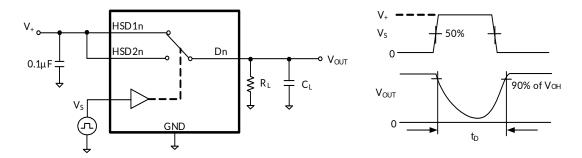


Figure 3. Break-Before-Make Time (t_D)



PARAMETER MEASUREMENT INFORMATION

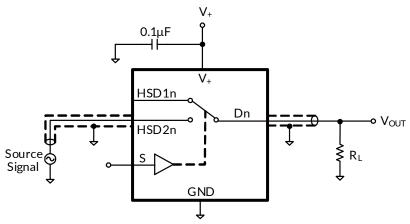
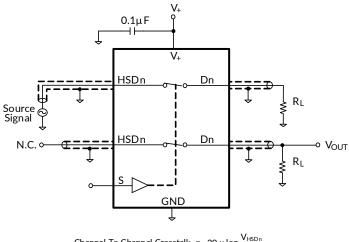


Figure 4. OFF Isolation (O_{ISO})



Channel To Channel Crosstalk = $-20 \times log \frac{V_{HSDn}}{V_{OUT}}$

Figure 5. Channel-to-Channel Crosstalk

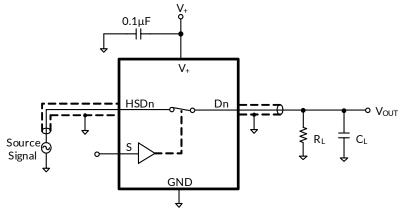


Figure 6. -3dB Bandwidth



PARAMETER MEASUREMENT INFORMATION

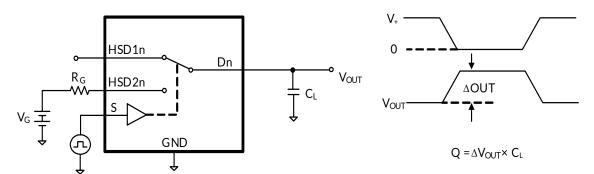


Figure 7. Charge Injection (Q)



10 APPLICATION NOTES

There are many USB applications in which the USB hubs or controllers have a limited number of USB I/Os. The RS2227 solution can effectively expand the limited USB I/Os by switching between multiple USB buses in order to interface them to a single USB hub or controller. RS2227 can also be used to connect a single controller to two USB connectors or controllers.

Design requirements of the USB 1.0, 1.1, and 2.0 standards should be followed. It is recommended that the digital control pins S and $\overline{\text{OE}}$ be pulled up to V+ or down to GND to avoid undesired switch positions that could result from the floating pin.

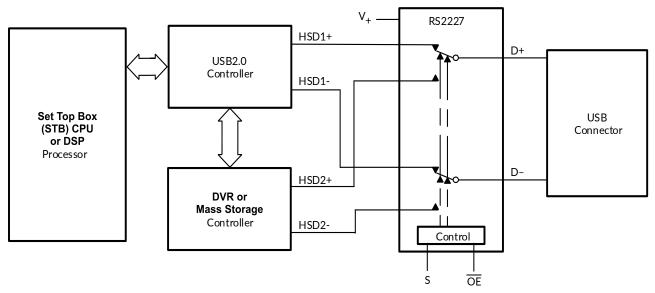
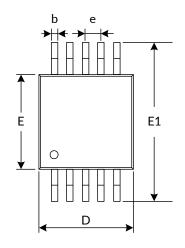
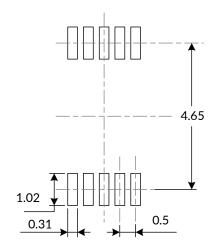


Figure 8. Application Diagram

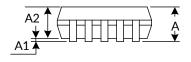


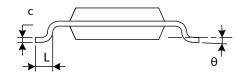
11 PACKAGE OUTLINE DIMENSIONS MSOP10 (3)





RECOMMENDED LAND PATTERN (Unit: mm)



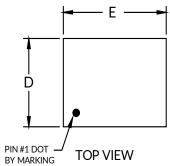


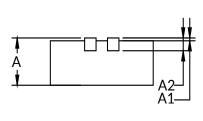
Symbol	Dimensions I	n Millimeters	Dimensions In Inches			
	Min	Max	Min	Max		
A (1)	0.820	1.100	0.032	0.043		
A1	0.020	0.150	0.001	0.006		
A2	0.750	0.950	0.030	0.037		
b	0.180	0.280	0.007	0.011		
С	0.090	0.230	0.004	0.009		
D (1)	2.900	3.100	0.114	0.122		
е	0.500(BSC) (2)	0.020(BSC) (2)			
E (1)	2.900	3.100	0.114	0.122		
E1	4.750	5.050	0.187	0.199		
L	0.400	0.800	0.016	0.031		
θ	0°	6°	6° 0°			

- 1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
- 2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
- 3. This drawing is subject to change without notice.



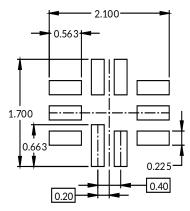
UQFN1.4X1.8-10⁽³⁾





SIDE VIEW

PIN#1 IDENTIFICATION CHAMFER 0.350 × 45°



RECOMMENDED LAND PATTERN

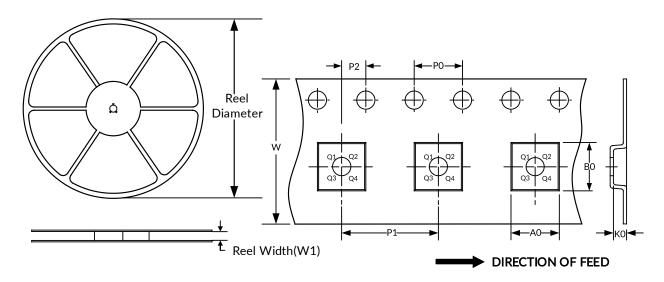
Symbol	Dimensions I	n Millimeters	Dimensions In Inches			
	Min	Max	Min	Max		
A (1)	0.500	0.600	0.020	0.024		
A1	0.000	0.050	0.000	0.002		
A2	0.203	REF (2)	0.008 REF ⁽²⁾			
a	0.050	0.150	0.150 0.002			
b	0.150	0.250	0.006	0.010		
С	0.450	0.550 0.018		0.022		
d	0.800	REF (2)	0.031 REF ⁽²⁾			
D (1)	1.350	1.450	1.450 0.053			
E (1)	1.750	1.850	0.069	0.073		
e	0.400) TYP	0.016 TYP			
L1	0.350	0.450 0.014		0.018		
L2	0.450	0.550 0.018		0.022		

- 1. Plastic or metal protrusions of 0.075mm maximum per side are not included.
- 2. REF is the abbreviation for Reference.
- 3. This drawing is subject to change without notice.



12 TAPE AND REEL INFORMATION REEL DIMENSIONS

TAPE DIMENSION



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
MSOP10	13"	12.4	5.20	3.30	1.20	4.0	8.0	2.0	12.0	Q1
UQFN1.4X1.8-10	7"	9.0	1.60	2.00	0.85	4.0	4.0	2.0	8.0	Q1

- 1. All dimensions are nominal.
- 2. Plastic or metal protrusions of 0.15mm maximum per side are not included.



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